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ON Semiconductor®

# **FDMC7692**

# N-Channel Power Trench<sup>®</sup> MOSFET General Description 30 V, 13.3 A, 8.5 m $\Omega$

#### **Features**

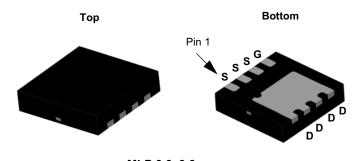
- Max  $r_{DS(on)}$  = 8.5 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 13.3 A
- Max  $r_{DS(on)}$  = 11.5 m $\Omega$  at  $V_{GS}$  = 4.5 V,  $I_D$  = 10.6 A
- High performance technology for extremely low r<sub>DS(on)</sub>
- Termination is Lead-free and RoHS Compliant

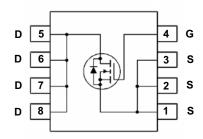


This N-Channel MOSFET is produced using ON Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance. This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery Packs.

#### **Application**

- DC DC Buck Converters
- Notebook battery power management
- Load switch in Notebook





MLP 3.3x3.3

#### **MOSFET Maximum Ratings** T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
$V_{DS}$	Drain to Source Voltage			30	V
$V_{GS}$	Gate to Source Voltage			±20	V
	Drain Current -Continuous (Package limited)	T <sub>C</sub> = 25 °C		16	
I <sub>D</sub>	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	13.3	Α
	-Pulsed			40	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	58	mJ
В	Power Dissipation	T <sub>C</sub> = 25 °C		29	W
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	2.3	VV
$T_J$ , $T_{STG}$	Operating and Storage Junction Temperature R	lange		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	4.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC7692	FDMC7692	MLP 3.3x3.3	13 "	12 mm	3000 units

# **Electrical Characteristics** $T_J$ = 25 °C unless otherwise noted

Parameter

Off Char	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0 V	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25 °C		16		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ = 24 V, $V_{GS}$ = 0 V $T_{J}$ = 125 °C			1 250	μА
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA

**Test Conditions** 

Тур

Max

Units

#### **On Characteristics**

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.2	1.9	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25 °C		-6		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 13.3 \text{ A}$		7.2	8.5	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 10.6 \text{ A}$		9.5	11.5	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 13.3 \text{ A}, T_J = 125 ^{\circ}\text{C}$		9.5	12.0	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DD</sub> = 5 V, I <sub>D</sub> = 13.3 A		60		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz	1260	1680	pF
C <sub>oss</sub>	Output Capacitance		480	635	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		65	100	pF
$R_g$	Gate Resistance		0.9	2.4	Ω

#### **Switching Characteristics**

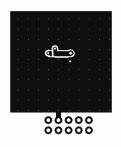
t <sub>d(on)</sub>	Turn-On Delay Time		9	18	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 15 V, I <sub>D</sub> = 13.3 A,	4	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_{GEN}$ = 6 $\Omega$	21	33	ns
t <sub>f</sub>	Fall Time		3	10	ns
0	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	21	29	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V}$	10	14	nC
$Q_{gs}$	Total Gate Charge	I <sub>D</sub> = 13.3 A	5		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		3		nC

#### **Drain-Source Diode Characteristics**

V	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 13.3 \text{ A}$	(Note 2)	0.86	1.2	V
v <sub>SD</sub>	Source to Drain Diode Torward voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1.9 A	(Note 2)	0.75	1.2	v
t <sub>rr</sub>	Reverse Recovery Time	I <sub>E</sub> = 13.3 A, di/dt = 100 A/μs		24	38	ns
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>F</sub> = 13.3 A, α//αι = 100 A/μs		7	14	nC

#### NOTES

<sup>1.</sup>  $R_{\theta JA}$  is determined with the device mounted on a 1 in 2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper

a minimum pad of 2 oz copper

b.125 °C/W when mounted on

- 2. Pulse Test: Pulse Width < 300  $\mu s,$  Duty cycle < 2.0 %.
- 3.  $E_{AS}$  of 58 mJ is based on starting  $T_J$  = 25 °C, L = 1 mH,  $I_{AS}$  = 10.8 A,  $V_{DD}$  = 27 V,  $V_{GS}$  = 10 V. 100% test at L = 0.1 mH,  $I_{AS}$  = 21 A.

# Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

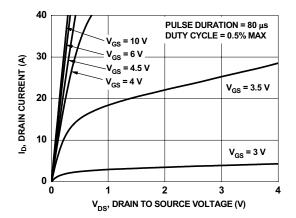


Figure 1. On-Region Characteristics

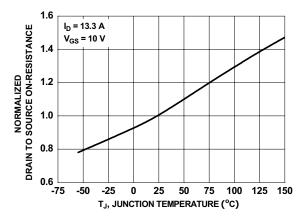


Figure 3. Normalized On-Resistance vs Junction Temperature

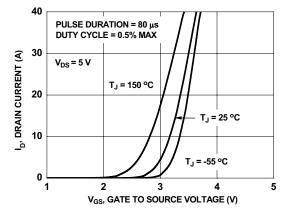


Figure 5. Transfer Characteristics

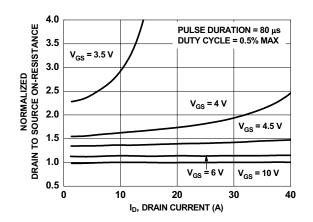


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

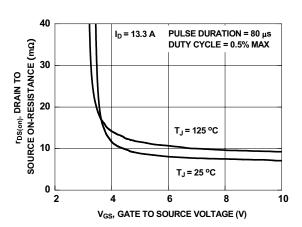


Figure 4. On-Resistance vs Gate to Source Voltage

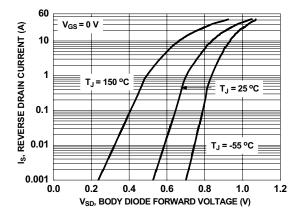


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

### **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

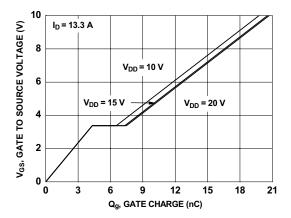


Figure 7. Gate Charge Characteristics

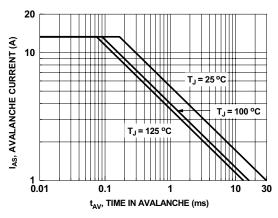


Figure 9. Unclamped Inductive Switching Capability

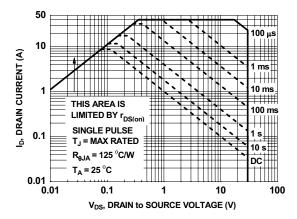


Figure 11. Forward Bias Safe Operating Area

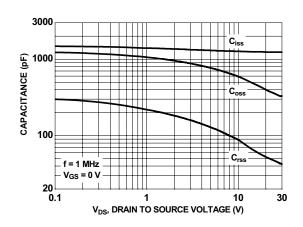


Figure 8. Capacitance vs Drain to Source Voltage

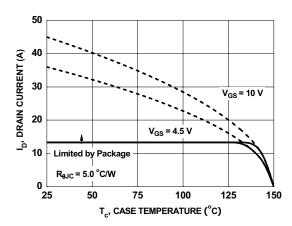


Figure 10. Maximum Continuous Drain Current vs Case Temperature

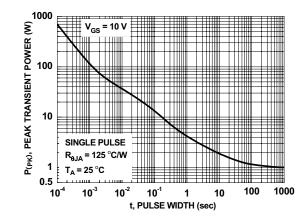


Figure 12. Single Pulse Maximum Power Dissipation

# Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

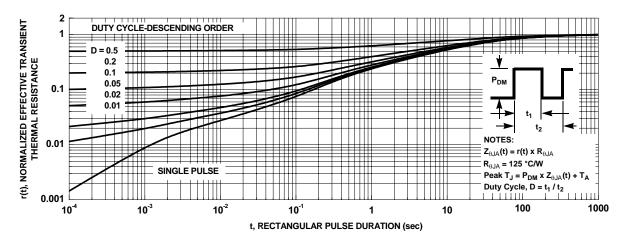


Figure 13. Transient Thermal Response Curve

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